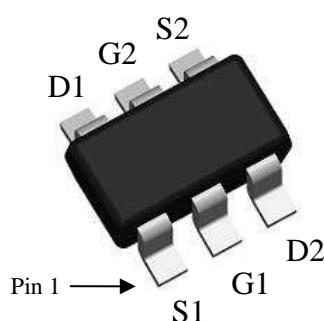


Dual N-Channel Enhancement Mode MOSFET

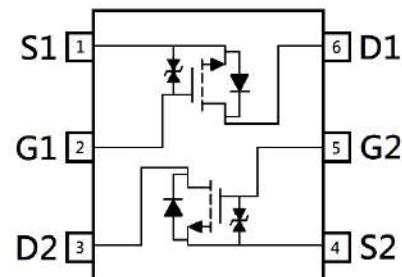
Features:

- ESD protected gate, typical 3kV (HBM)
- High speed switching
- Easily designed drive circuits
- Low-voltage drive
- Easy to use in parallel
- RoHS compliant package

SOT-363



BV_{DSS}	30V
$I_D @ V_{GS}=10V, T_A=25^\circ C$	0.47A
$R_{DS(ON)} \text{ typ.} @ V_{GS}=10V, I_D=0.2A$	0.4Ω
$R_{DS(ON)} \text{ typ.} @ V_{GS}=4.5V, I_D=0.2A$	0.5Ω
$R_{DS(ON)} \text{ typ.} @ V_{GS}=2.5V, I_D=0.2A$	0.9Ω



G : Gate S : Source D : Drain

Ordering Information

Device	Package	Shipping
KWDK8R	SOT-363 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_A=25^\circ\text{C}$	I_D	0.47	A
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_A=70^\circ\text{C}$		0.38	
Pulsed Drain Current	I_{DM}	1.9	
Continuous Body Diode Forward Current @ $T_A=25^\circ\text{C}$	I_S	0.2	
ESD susceptibility	V_{ESD}	3000	V
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	0.3	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$

Note:

*a. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$. Ratings are based on low frequency and low duty cycles to keep initial $T_J=25^\circ\text{C}$.

*b. Human body model, $1.5\text{k}\Omega$ in series with 100pF .

Electrical Characteristics ($T_A=25^\circ\text{C}$, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	30	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	0.7	-	1.6		V _{DS} =V _{GS} , I _D =250μA
G _{FS}	-	0.5	-	S	V _{DS} =5V, I _D =0.2A
I _{GSS}	-	-	±10		V _{GS} =±16V, V _{DS} =0V
I _{DSS}	-	-	1	μA	V _{DS} =24V, V _{GS} =0V
R _{D(S(ON))}	-	0.4	0.8		V _{GS} =10V, I _D =0.2A
	-	0.5	1.3		V _{GS} =4.5V, I _D =0.2A
	-	0.9	6.5		V _{GS} =2.5V, I _D =0.2A
Dynamic					
C _{iss}	-	27	-	pF	V _{DS} =15V, V _{GS} =0V, f=1MHz
C _{oss}	-	12	-		
C _{rss}	-	8	-		
Q _g *1, 2	-	1.7	-	nC	V _{DS} =15V, I _D =0.2A, V _{GS} =10V
Q _{gs} *1, 2	-	0.7	-		
Q _{gd} *1, 2	-	0.3	-		
t _{d(ON)} *1, 2	-	3.2	-	ns	V _{DS} =15V, I _D =0.2A, V _{GS} =10V, R _{GS} =1Ω
t _r *1, 2	-	16	-		
t _{d(OFF)} *1, 2	-	10	-		
t _f *1, 2	-	14	-		
Source-Drain Diode					
V _{SD} *1	-	0.8	1.2	V	I _S =0.2A, V _{GS} =0V
trr	-	5	-	ns	I _F =0.2A, dI _F /dt=100A/μs
Qrr	-	1.2	-		

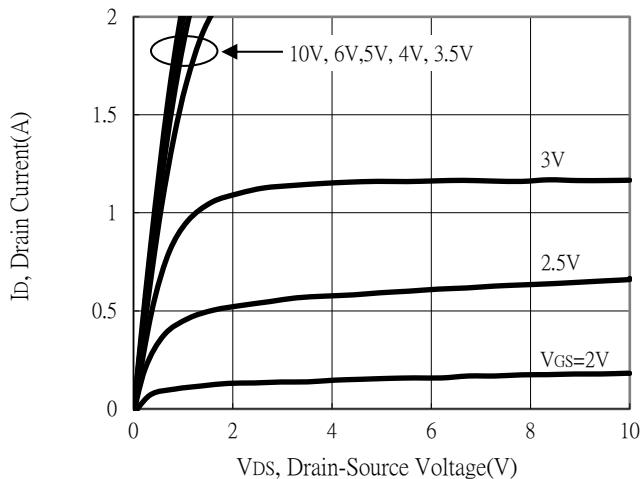
Note:

*1. Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

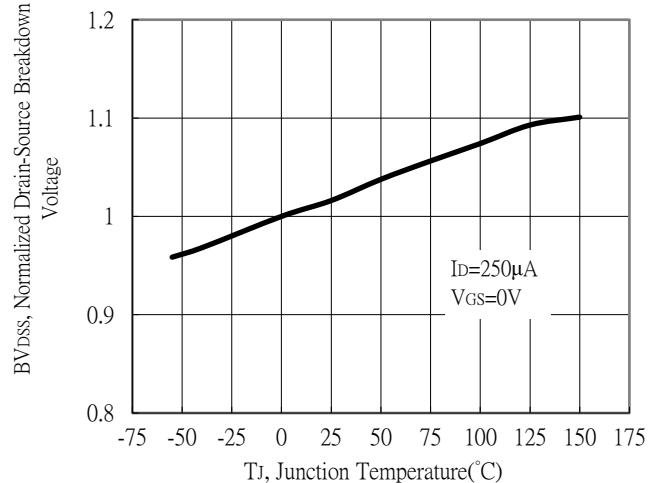
*2. Independent of operating temperature

Typical Characteristics

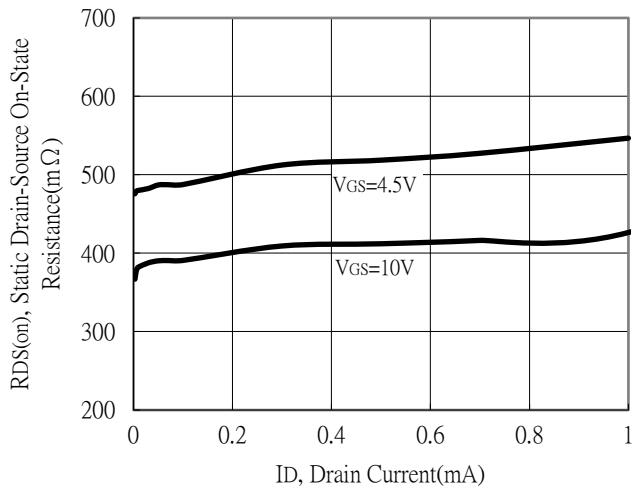
Typical Output Characteristics



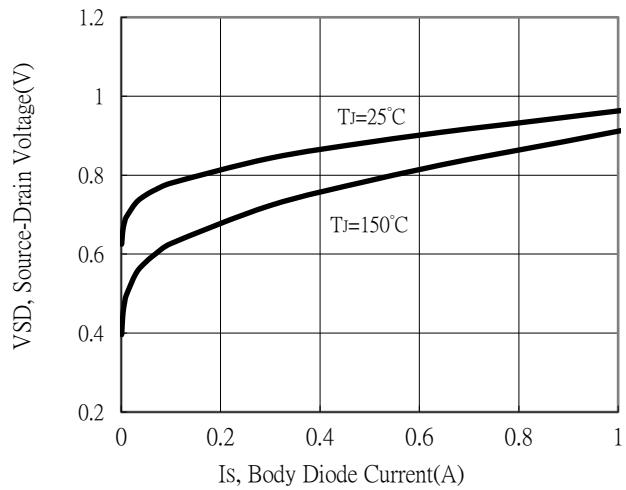
Breakdown Voltage vs Ambient Temperature



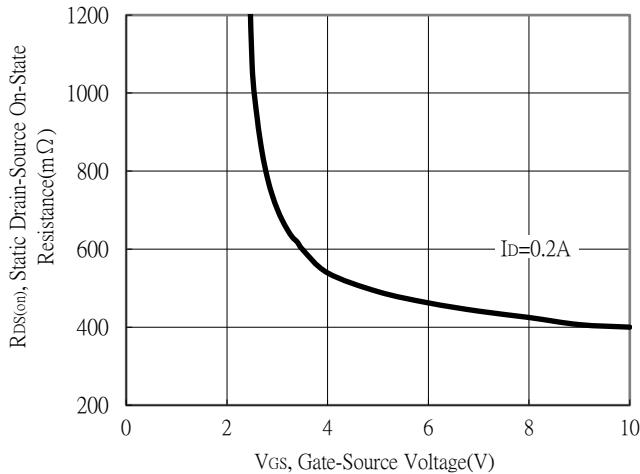
Static Drain-Source On-State resistance vs Drain Current



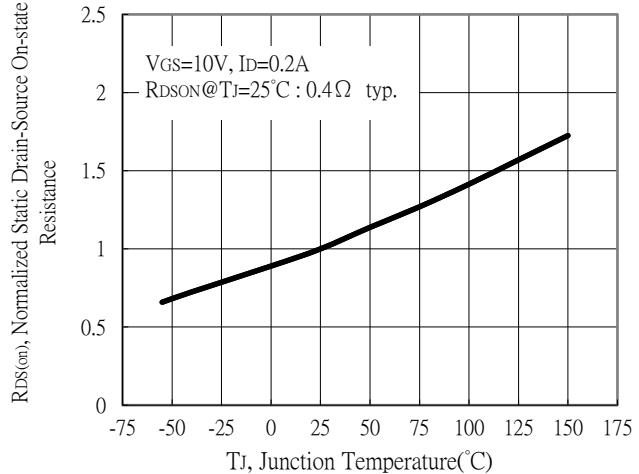
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

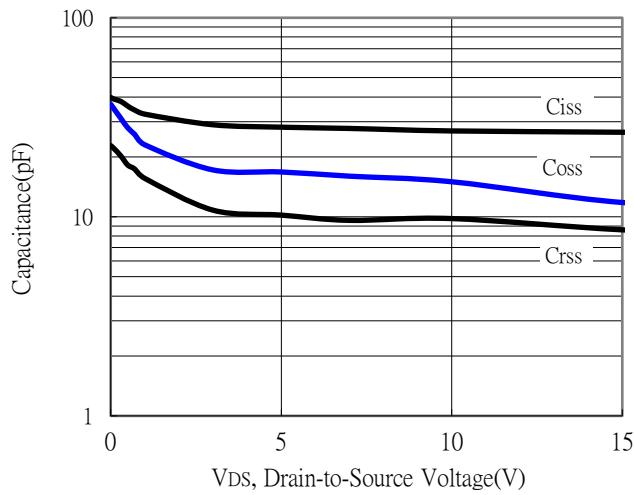


Drain-Source On-State Resistance vs Junction Temperature

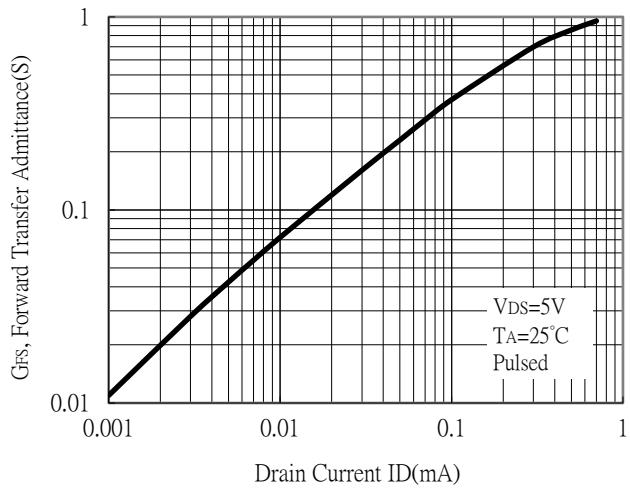


Typical Characteristics (Cont.)

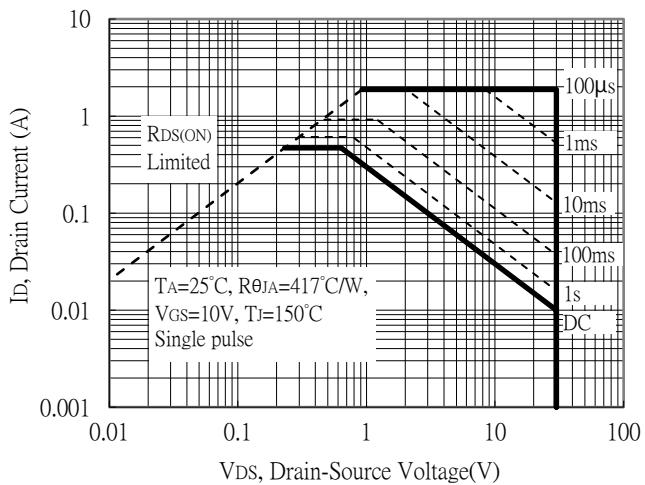
Capacitance vs Drain-to-Source Voltage



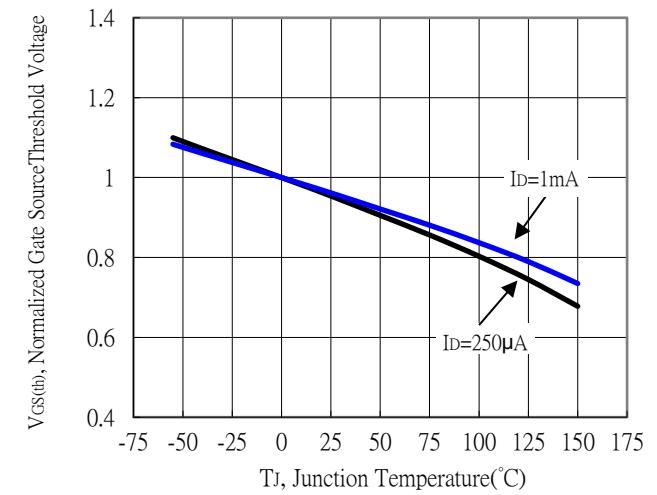
Forward Transfer Admittance vs Drain Current



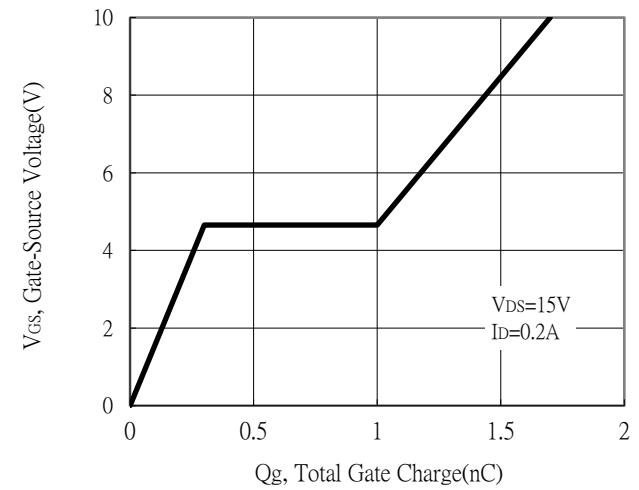
Maximum Safe Operating Area



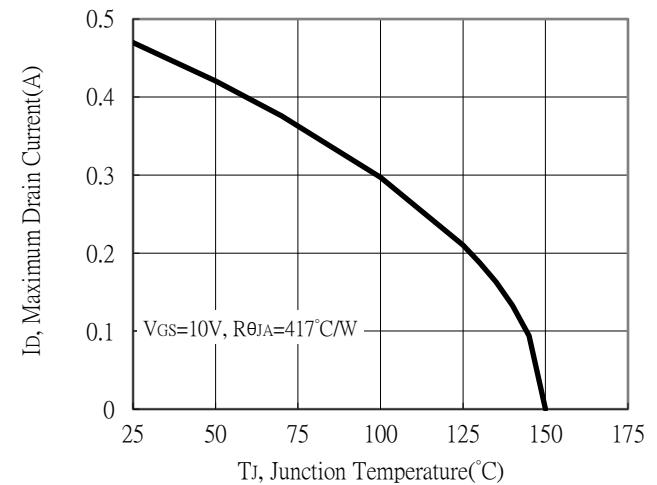
Threshold Voltage vs Junction Temperature



Gate Charge Characteristics

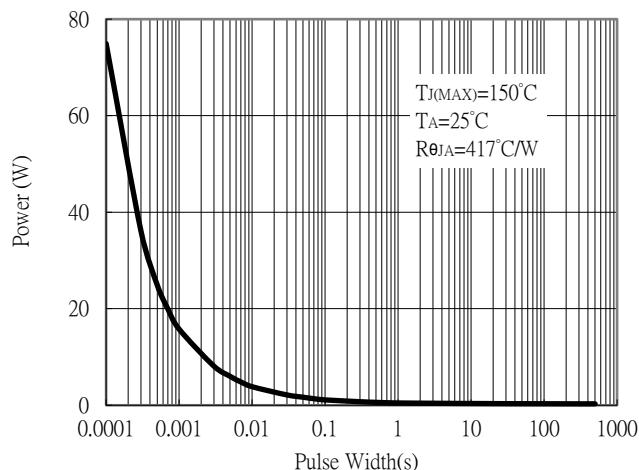


Maximum Drain Current vs Junction Temperature

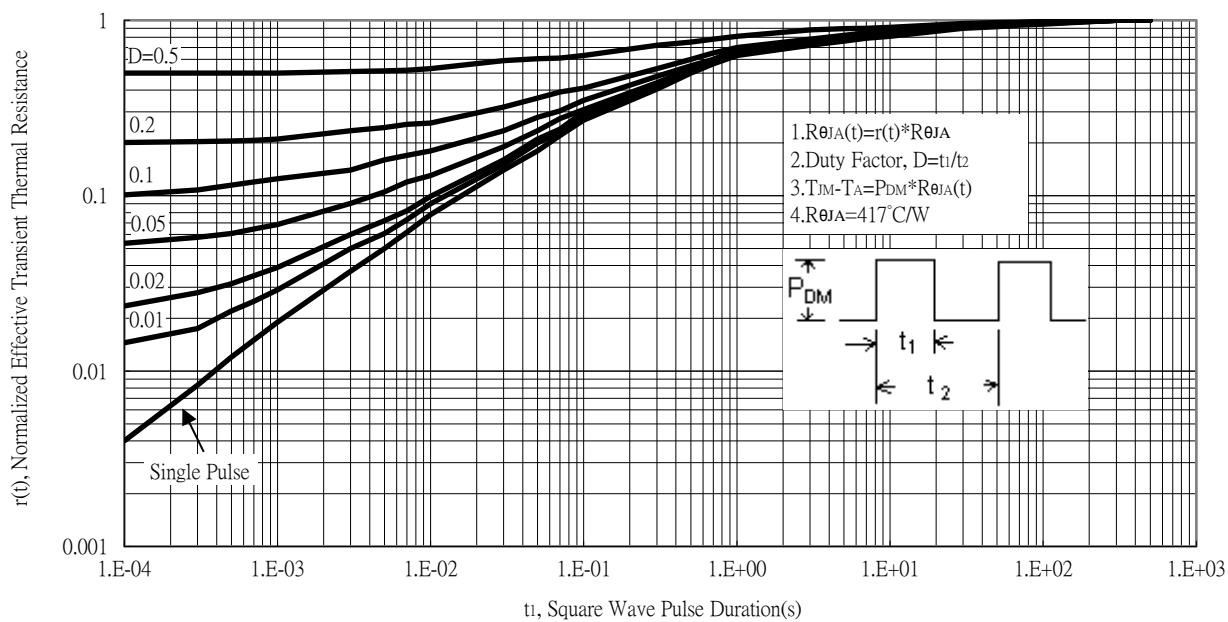


Typical Characteristics (Cont.)

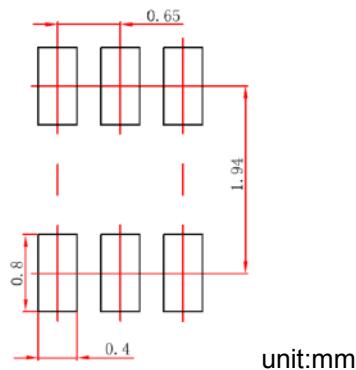
Single Pulse Power Rating, Junction to Ambient



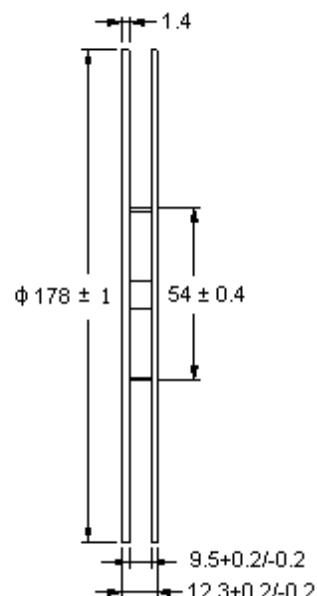
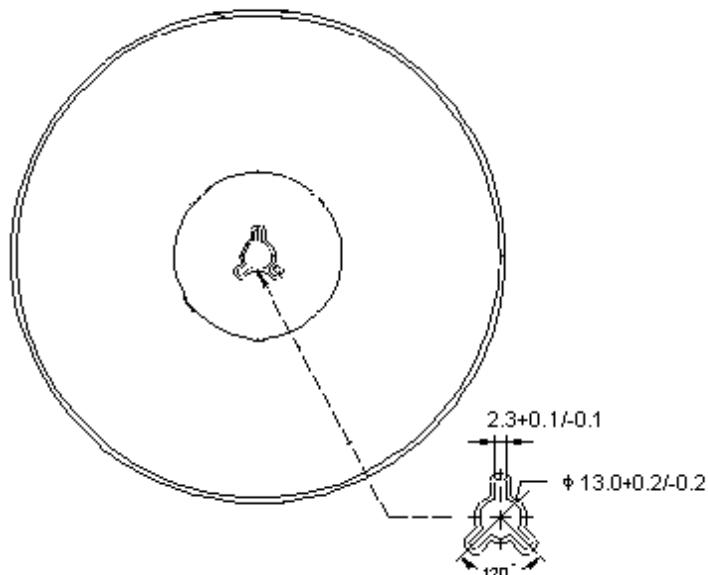
Transient Thermal Response Curves



Recommended Soldering Footprint

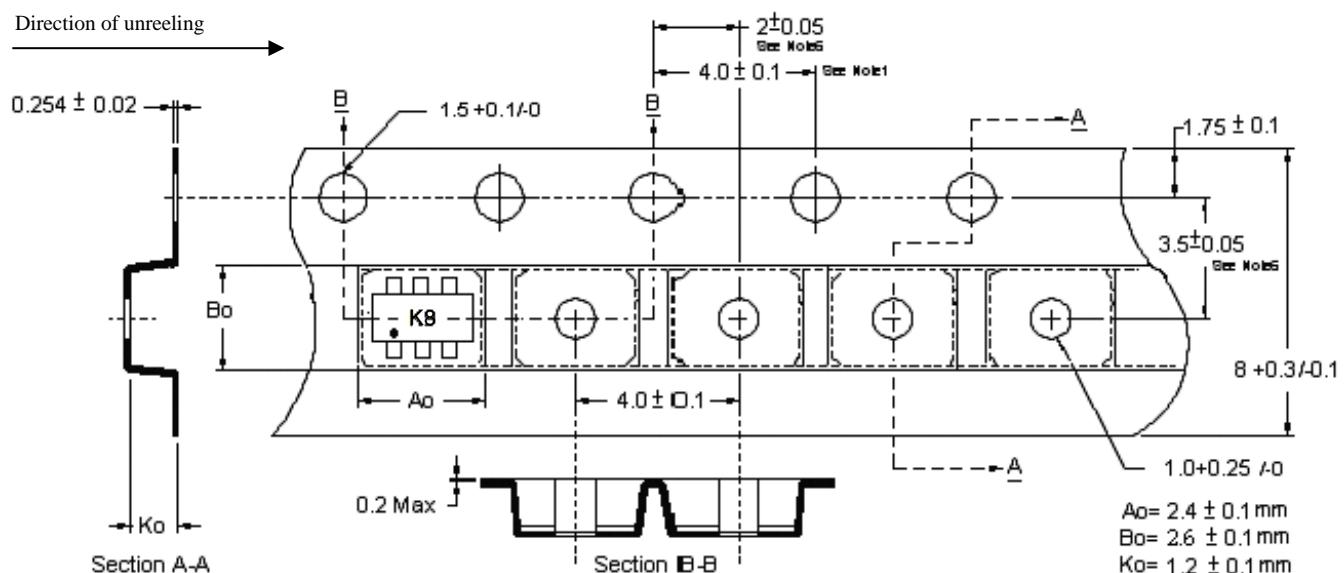


Reel Dimension



Unit: millimeter

Carrier Tape Dimension

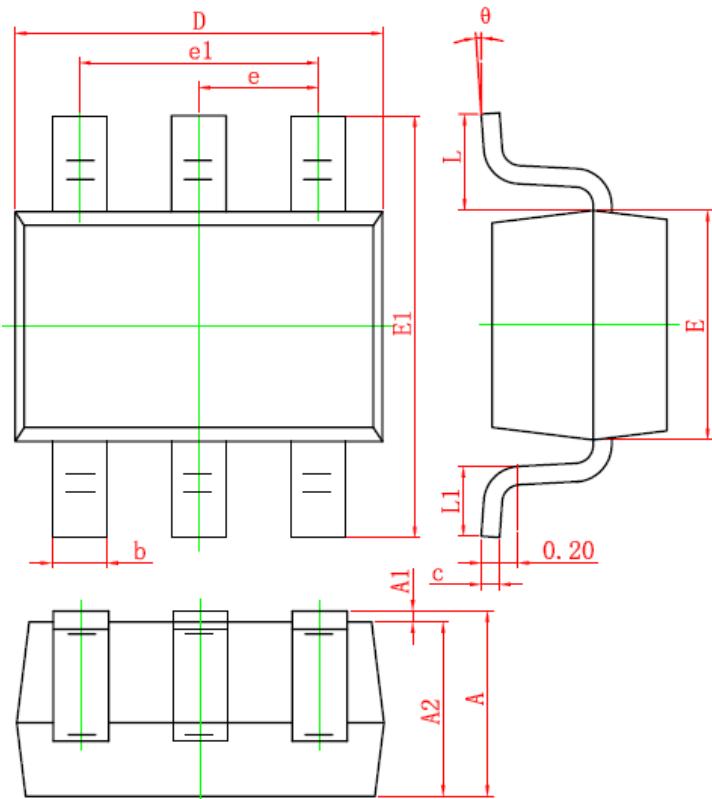


Notes:

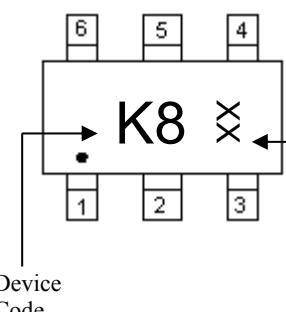
1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Polystyrene.
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

SOT-363 Dimension



Marking:



Date Code:
 Year + Month
 Year : 9→2019,
 0→2020,..., etc

Month : 1→Jan
 2→Feb, ..., 9→
 Sep, A→Oct, B
 →Nov, C→Dec

6-Lead SOT-363 Plastic
 Surface Mounted Package

Style:

- Pin 1. Source1 (S1)
- Pin 2. Gate1 (G1)
- Pin 3. Drain2 (D2)
- Pin 4. Source2 (S2)
- Pin 5. Gate2 (G2)
- Pin 6. Drain1 (D1)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650	TYP	0.026	TYP
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525	REF	0.021	REF
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					